



苏州群力欣光电科技有限公司

Suzhou Que-lesion Optoelectronic Technology co.,Ltd

产品规格书

SPECIFICATION

| | | | |
|----------------------|-------------|-----------------|-----------------|
| 客户名称 Customer | | 产品名称 Product | 3528LED |
| 客户料号 Customer No. | | 产品型号 Type | QSTRRB4-01-20MA |
| 规格书编号 SPEC No | 20150416001 | 日期 Date | 2015.04.16 |

| | | |
|--------------------------------|--|--|
| 客 户 确 认 APPROVED SIGNATURES | | |
| | | |

制定(DRAW): _____ 审核(CHECK): _____ 批准 (APPROVE): _____

地址:江苏省苏州市相城区阳澄湖镇石田路 3 号

ADD:NO.3 shitian road,yangchenhu town,xiangcheng district,Suzhou,china

电话(Tel): 0512-69599058

传真(Fax):0512-65485461



QSTRRB4-01-20MA

特征 Features

- 宽的发光角度
Extremely wide viewing angle
- 适合所有 SMT 组装和焊接过程
Suitable for all SMT assembly and solder process
- 可用在载带及卷轴上
Available on tape and reel
- 防潮等级:2 级
Moisture sensitivity level: Level 2
- 包装:2000pcs/卷
Package:2000pcs/reel
- 符合欧盟 RoHS 标准
RoHS compliant

描述 Description

红光 LED 由 AlGaInP 四种元素芯片激发而成

The red source color devices are made with AlGaInP on Substrate Light Emitting Diode

应用 (Applications)

光学指示

Optical indicator

室内显示

Indoor display

汽车照明

Automotive lighting

LCD 背光、转换器，开关和标志，显示器等 Backlight for LCD , switch and symbol , display

用于日光灯管

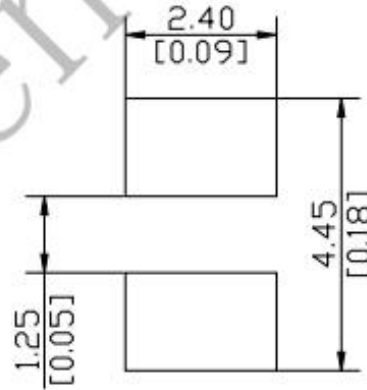
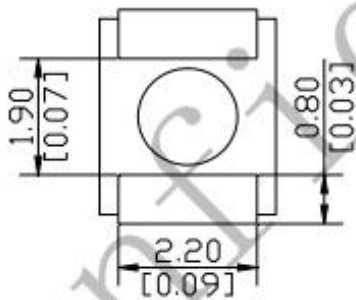
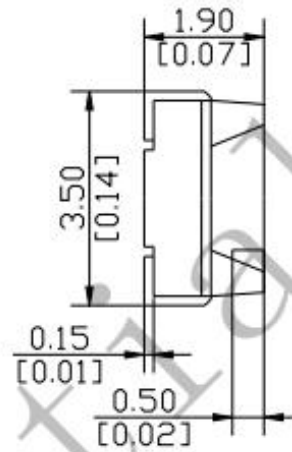
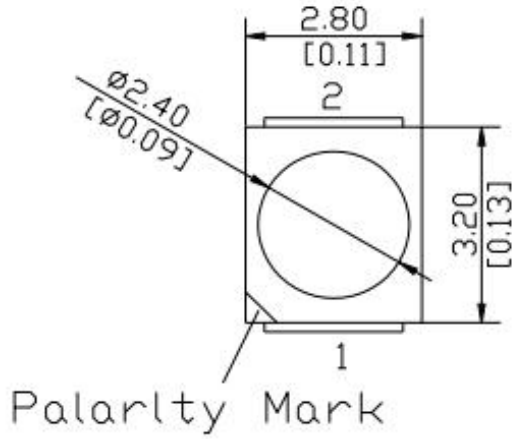
Tubular light application

一般应用

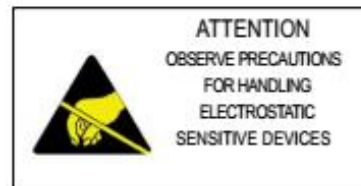
General use

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外形尺寸 Outline Dimensions



Soldering Patterns



NOTES:

1. All dimensions units are millimeters. (所有尺寸标注单位为毫米)
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted. (除特别标注外, 所有尺寸公差为 ± 0.2 毫米)



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Electrical / Optical Characteristics at Ta=25°C 电性与光学特性

| Item 项目 | Symbol 符号 | test condition 测试条件 | Value | | | unit 单位 | |
|---------------------|--------------|------------------------|---------|-------|-------|------------|-----|
| | | | Min. | Max. | Typ. | | |
| Forward Voltage | Rank B1 | Vf | IF=20mA | 1.8 | 1.9 | --- | V |
| | Rank C2 | | | 1.9 | 2.0 | --- | V |
| | Rank C1 | | | 2.0 | 2.1 | --- | V |
| | Rank C2 | | | 2.1 | 2.2 | --- | V |
| | Rank D1 | | | 2.2 | 2.3 | --- | V |
| | Rank D2 | | | 2.3 | 2.4 | --- | V |
| Dominant wavelength | Rank D20 | λd | IF=20mA | 617.5 | 620 | --- | nm |
| | Rank E10 | | | 620 | 622.5 | --- | nm |
| | Rank E20 | | | 622.5 | 625 | --- | nm |
| | Rank F10 | | | 625 | 627.5 | --- | nm |
| | Rank F20 | | | 627.5 | 630 | --- | nm |
| Luminous intensity | Rank 1AT | IV | IF=20mA | 200 | 260 | --- | mcd |
| | Rank 1AU | | | 260 | 330 | --- | mcd |
| | Rank 1AV | | | 330 | 430 | --- | mcd |
| Reverse Current | VR=5V | IR | --- | 10 | --- | uA | |
| Viewing Angle | 2Θ1/2 | IF=20mA | --- | --- | 120 | Deg | |
| Thermal resistance | Rth(j-s) | IF=20mA | --- | --- | 80 | °C/W | |

Absolute Maximum Ratings at Ta=25°C 绝对最大值

| Parameter (参数) | Symbol (符号) | Rating (值) | Units (单位) |
|-----------------------------------|-------------|------------|------------|
| Power Dissipation (功耗) | Pd | 70 | mW |
| Forward Current (正向电流) | IF | 30 | mA |
| Peak Forward Current (峰值电流) | IFP | 100 | mA |
| Reverse Voltage (反向电压) | VR | 5 | V |
| Electrostatic Discharge(HBM) (静电) | ESD | 2000 | V |
| Operating Temperature (操作温度) | Topr | -40 ~ +85 | °C |
| Storage Temperature (储存温度) | Tstg | -40 ~ +100 | °C |
| junction temperature (结温) | Tj | 115 | °C |

Note: 1. 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms, 周期1/10.

2. The above forward voltage measurement allowance tolerance is 0.1V. 以上所示电压测量误差0.1V.

3. The above wavelength measurement allowance tolerance is ±1nm. 以上所示波长测量误差±1nm.

4. the above luminous intensity measurement allowance tolerance ±10%. 上述发光强度的测试允许公差为±10%.

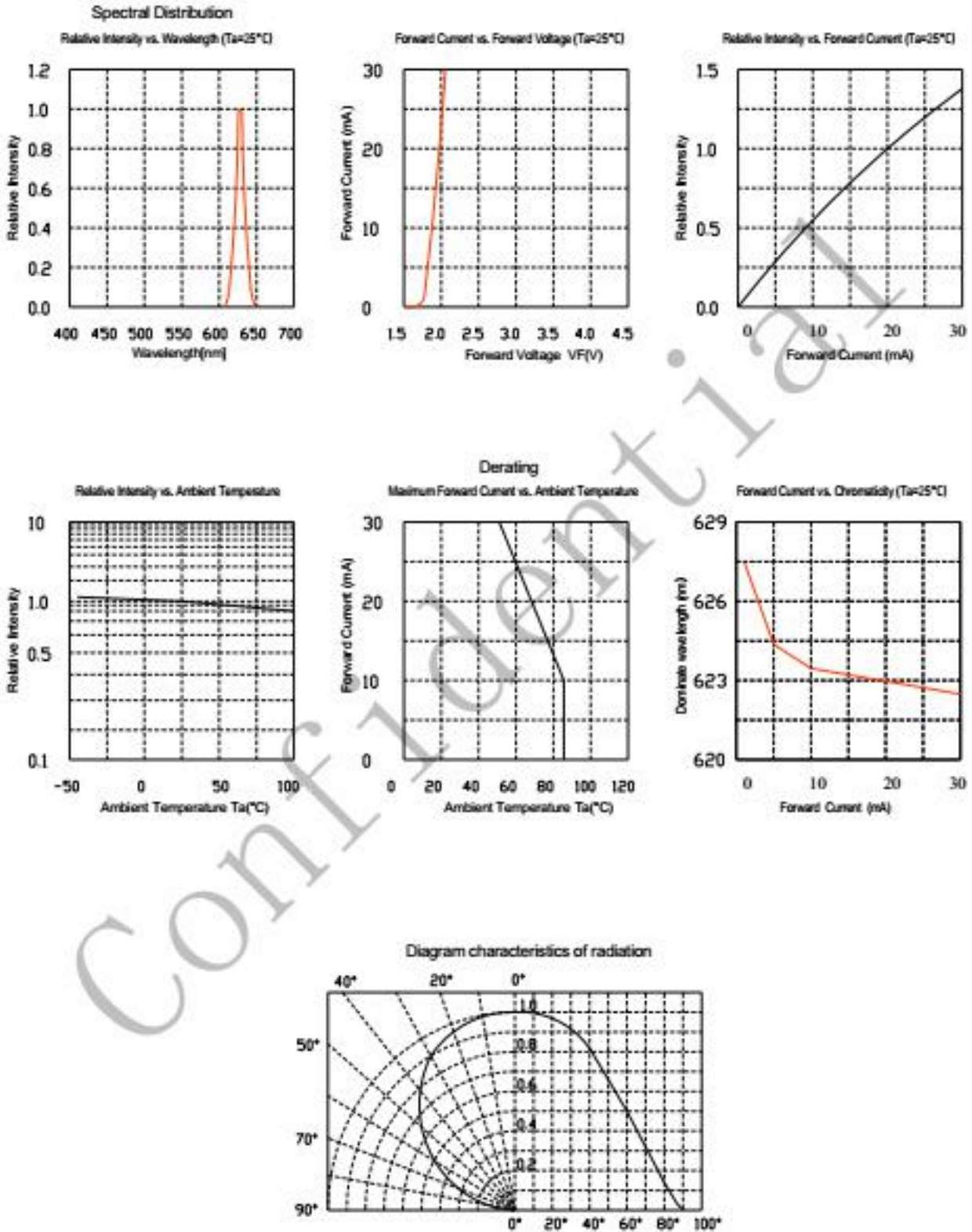
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值。

6. All measurements were made under the standardized environment of Refond. 所有测试都是基于瑞丰现有的标准测试平台。

7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED使用的最大电流需要根据散热条件确定, 结温不能超过最大值。

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Typical optical characteristics curves 典型光学特性曲线





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信赖性测试项目及条件 Reliability Test Item And Conditions

| Test Items 项目 | Ref.Standard 参考标准 | Test Condition 测试条件 | Time 时间 | Quantity 数量 | Ac/Re 接收/拒收 |
|---|----------------------|---|------------|----------------|----------------|
| Reflow 回流焊 | JESD22-B106 | Temp:260°C max T=10 sec | 2times. | 22Pcs. | 0/1 |
| Temperature Cycle 温度循环 | JESD22-A104 | 100°C 30 min. ↑↓5 min -40°C 30 min. | 100 Cycles | 22Pcs. | 0/1 |
| Thermal Shock 冷热冲击 | JESD22-A106 | -40°C 15min ↑↓ 100°C 15min | 300 cycle | 22Pcs. | 0/1 |
| High Temperature Storage 高温保存 | JESD22-A103 | Temp:100°C | 1000Hrs. | 22Pcs. | 0/1 |
| Low Temperature Storage 低温保存 | JESD22-A119 | Temp:-40°C | 1000Hrs. | 22Pcs. | 0/1 |
| Life Test 常温通电 | JESD22-A108 | Ta=25°C IF=20mA | 1000Hrs. | 22Pcs. | 0/1 |
| High Temperature High Humidity Life Test 高温高湿通电 | JESD22-A101 | 60°C / 90%RH IF=20mA | 1000Hrs. | 22Pcs. | 0/1 |

失效判断标准 Criteria For Judging Damage

| Test Items 项目 | Symbol 符号 | Test Condition 测试条件 | Criteria For Judgement 判定标准 | |
|----------------------------|--------------|------------------------|--------------------------------|-------------|
| | | | Min. 最小 | Max. 最大 |
| Forward Voltage 正向电压 | VF | IF=20mA | - | U.S.L*)x1.1 |
| Reverse Current 反向电流 | IR | VR = 5V | - | U.S.L*)x2.0 |
| Luminous Intensity 发光强度 | mcd | IF=20mA | L.S.L*)x0.7 | - |

备注 Note:

Tsol-锡液温度; I_{FT}:典型电流 Tsol –Temperature of tin liquid ; I_{FT}:Typical current

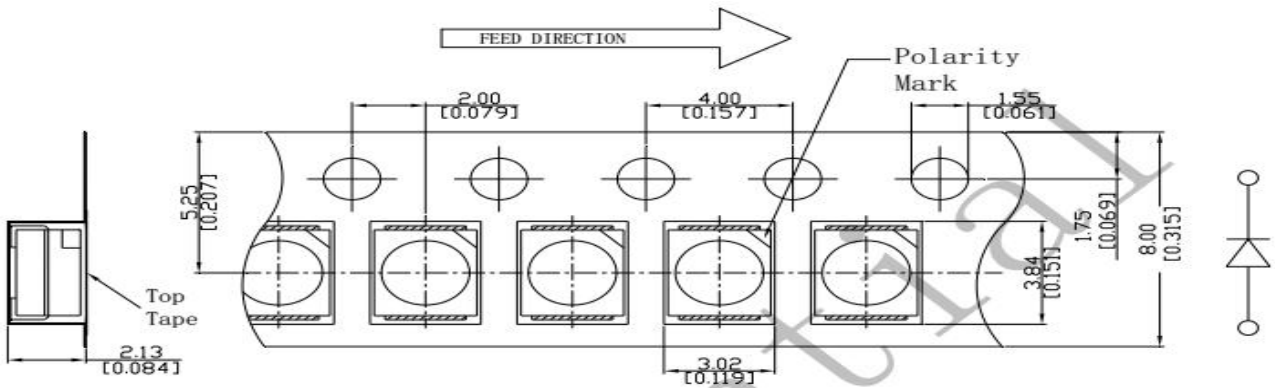
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包装 Packaging

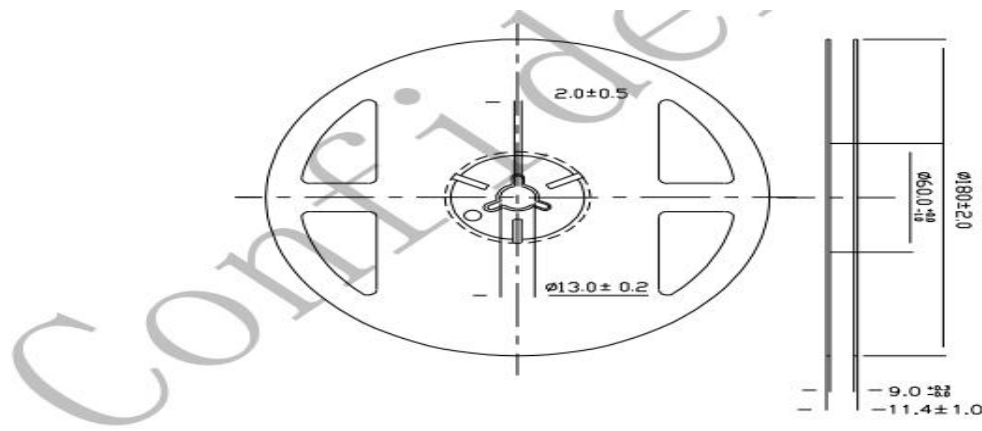
标签 Label

料号 Part No.:*** 批号 Lot No.:*** 数量 O'ty(pcs):***
 亮度 Iv(mcd):*** 波长 (nm) :*** 电压 VF (v) :***
 日期 Date:***

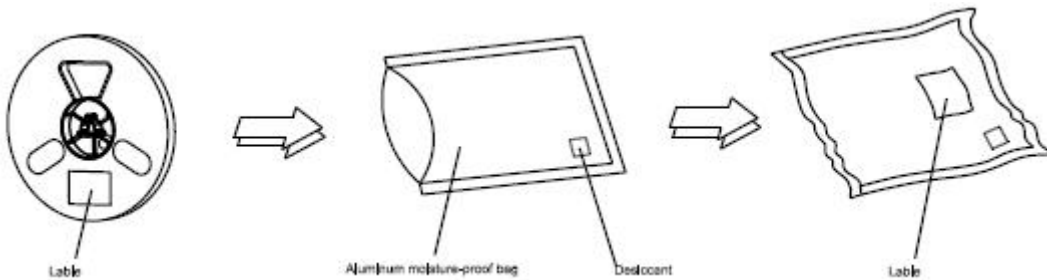
载带规格 (单位: mm) Tape Specifications(Units:mm)



卷轴尺寸 Reel Dimensions



防潮袋包装 Moisture Resistant Packaging



备注: 标注公差为 ± 0.1 mm,单位: mm

Note : The tolerances unless mentioned is ± 0.1 mm,Unit:mm

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焊接指导 Guideline for Soldering

Soldering iron 烙铁焊接

1. When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds

当手工焊接时，烙铁的温度必须小于300℃，时间不可超过3秒

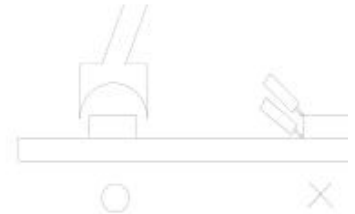
2. The hand solder should be done only one times

手工焊接只可焊接一次

Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED回流焊后不应该修复，当修复是不可避免时，必须使用双头烙铁（如下图），但必须事先确认此种方式会或不会损坏LED本身的特性。

**Cautions 注意事项**

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

LED封装为硅胶，故LED胶体表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在封装的零件上的强大压力，当使用吸嘴时，胶体表面的压力应是恰当的。

3. Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry

不可将模组材料堆积在一起，它可能会损坏内部电路

4. Not suitable to operate in acidic environment, PH<7

不可用在PH<7的酸性场所

